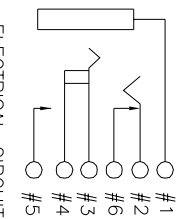
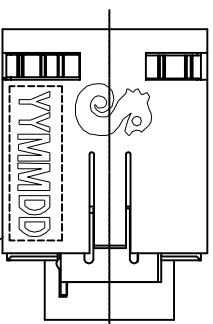


RECOMMENDED PCB LAYOUT



REVERSE ELECTRICAL CIRCUIT



DATE CODE

- SPECIFICATIONS:**
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE: 30mΩ MAX.
 - INSULATION VOLTAGE WITHSTAND: 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE: 0.4 - 3kg.
 - WITHDRAWAL FORCE: 0.3 - 2kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "S" ON TOP OF CONNECTOR.
 - PACKING: TAPE & REEL.
 - TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE"
 - GREEN PRODUCT IDENTIFICATION MARK IN JACK: **G.P. PASS**
 - GREEN PRODUCT IDENTIFICATION LABEL IN PACKING:
 - FOR LEAD-FREE PROCESS.
 - RESISTANT TO SOLDER HEAT:DIP WAVE SOLDER 270 C MAX,5 SEC SMT IR REFLOW 260 C, 5 SEC

REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	JERRY	2006.04.28
B	ECN:S160754-C	JIE-FU	2016.09.21

H	SHIELDING	1	C3191-H 0.2l	NICKEL PLATING
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2l	SILVER PLATING
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2l	SILVER PLATING
E	SHUNT TERMINAL -A	1	BRASS 0.25l	SILVER PLATING
D	RING SPRING	1	PHOSPHOR BRONZE 0.2l	SILVER PLATING
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25l	SILVER PLATING
B	EARTH	1	COPPER ALLOY 0.3l	SILVER PLATING
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	PINK (701C)
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X : ±0.5	X : ±2°
X.X : ±0.3	X.X : ±1°
X.XX : ±0.2	

Singatron Enterprise Co., Ltd.
信登企業股份有限公司

TITLE	3.5φ PHONE JACK
DWN	JIE-FU PART NO. 2SJ-S351-014
CHKD	CERRY SCALE: 4/1 UNIT: mm
APVD	LUSSSEN SIZE: A3 SHEET: 1 OF 1 REV: B

CUSTOMER COPY